

CONFERENCE

IN PERSON

ACTIVE

PlatCon 2026 : 2026 International Conference on Platform Technology and Service

LOCATION	SUBJECT / TOPIC	EVENT DATES	LAST UPDATED
N/A	General	August 24-26, 2026	1st July, 2026

DESCRIPTION

Overview

PlatCon-26 will be the 12th event of the PlatCon conference series, co-hosted by the Institution of Creative Research Professionals (ICRP) and National Center of Excellence in Software, Shinhan University. This year's event will be technically co-sponsored by IEEE Busan section.

This conference will be one of the most comprehensive conferences in the field of Platform Technology (PT). The main focus of PlatCon-26 is various research issues in Platform Technology; however its scope also extends to a wide spectrum of topics related to Computer Science and ICT platforms and their service domains. PlatCon-26 will be a professional and informative forum for scientists, engineers, experts, professors, and students in the areas of Computer Science, Information Technology, Computing Technology, Communication and Networking, HCI, Business and Management, Intelligent Systems, Cybersecurity, Industrial Security, Cyber-Physical Systems, Educational Technology, IT-based convergence research fields, as well as multidisciplinary and interdisciplinary research fields.

Over the last decade, many countries have adopted roadmaps for developing future infrastructure in emerging platform technology areas such as automobiles, big data processing, biotechnology, nanotechnology, grid computing, and ICT (Information and Communication Technology). Our special interest lies in both theoretical and practical research contributions, including new techniques, concepts, or analyses; reports on implementation experiences and experimental results; and tutorials on emerging technologies and trends in platform and service areas, as well as related scientific and engineering fields.

PlatCon-26 is the next event in a series of highly successful International Conferences on Platform Technology and Service, previously held as PlatCon-25 (Jeju, Korea, Aug. 2025), PlatCon-24 (Jeju, Korea, Aug. 2024), PlatCon-23 (Busan, Korea, Aug. 2023), PlatCon-22 (Jeju, Korea,

KEY DEADLINES

Submission	17th Jul, 2026
Notification	31st Jul, 2026
Camera Ready	7th Aug, 2026
Conference	24th Aug, 2026

OFFICIAL LINKS

[Visit Submission Page](#)

CALL FOR PAPER URL

<https://callforpaper.org/cfp/call-for-papers-platcon-2026>

Aug. 2022), PlatCon-21 (Jeju, Korea, Aug. 2021), PlatCon-19 (Jeju, Korea, Jan. 2019), PlatCon-18 (Jeju, Korea, Jan. 2018), PlatCon-17 (Busan, Korea, Feb. 2017), PlatCon-16 (Jeju, Korea, Feb. 2016), PlatCon-15 (Jeju, Korea, Jan. 2015), and PlatCon-14 (Jeju, Korea, Feb. 2014).

Conference Topics

PlatCon-26 covers all Computer Science and ICT areas with their convergence topics as below:

[Computing Platform]

- Computing theory
- Computer architecture
- Grid and cloud computing and systems
- Distributed and parallel computing systems
- Embedded computing and systems
- Fault-tolerant computing and systems
- Ubiquitous computing and systems
- Operation systems
- Secure OS and Trust OS

[Networking Platform]

- Ad hoc and sensor network platform
- Broadband communication platform
- Microwave communication platform
- Mobile and wireless platform
- Satellite communication platform
- Smart home and M2M (machine to machine) network
- System and network management and troubleshooting
- Vehicular communication platform
- Software defined network

[Smart Human & Media Platform]

- Game platform
- Interaction and HCI
- Media art convergence
- Multimedia platform
- Scientific and big data visualization platform
- Smart UI/UX platform
- Virtual and augmented reality
- E-Learning & U-Learning platform
- Web platform
- Artificial intelligence platform
- Automobile platform
- Big data platform
- Semantic web technology platform

[Convergence Platform]

Business service platform
Business management and intelligence
Internet of things
Service innovation and entrepreneurship
Service oriented computing and applications
Social networks
Security and privacy issues in emerging platforms
Convergence security
Cyber security and digital forensics
Smart grid and its security
Financial platform

Important Dates

- Paper Submission Due : Wednesday, 24 June 2026 Friday, 17 July 2026
 - Authors Notification : Friday, 03 July 2026 Friday, 31 July 2026
 - Camera-Ready Paper Due : Friday, 10 July 2026 Friday, 07 August 2026
 - Author Registration Due : Friday, 10 July 2026 Friday, 07 August 2026
 - Conference Dates : Monday, 24 August - Wednesday, 26 August, 2026
- All deadlines are at 23:59 (KST, Korea Standard Time).

Paper Submission and Review

EDAS is the official conference tool for PlatCon-26.
Authors should submit their papers to the following EDAS system for review: <https://edas.info/N35293>
Further information about the paper submission, please visit <https://www.platcon.org/cfp>

Publications

Conference Proceedings : At least three reviewers of the International Technical Program Committee will carefully review each submitted paper. The accepted papers to the main conference "Track 1" and the official workshops will be included in the Conference Proceedings which will be distributed on the site and then submitted to the IEEE Xplore (No-show papers will be excluded in submission to IEEE Xplore). "Track 2" papers will not be included in the IEEE conference proceedings, but they will be presented at the conference and then published in PTL, Platform Technology Letters, which is an distinguished international journal published by ICRP and ICTPS.

Conference Program Book : The Abstract Texts of the accepted papers will be included in the Conference Program Book and it will be distributed at the conference via online and also on the site.

Some selected papers will be recommended for publication in the special issues of the following journals:

- CMC-Computers Materials & Continua:

https://www.techscience.com/cmc/special_detail/data-intensive_computing_llms

- Electronics (MDPI):

https://www.mdpi.com/journal/electronics/special_issues/925C215FY6

https://www.mdpi.com/journal/electronics/special_issues/G6K9AWWJVG
etc.

We will also be offering discounts on Article Publication Charges for a limited number of papers.

Contact Information

If you have enquiries about the conference, please contact one of the following conference chairs: Byoungjin Seok (bjseok@hansung.ac.kr), Jaehwan Lee (jhnlee@kongju.ac.kr), or Dongwann Kang (dongwann@seoultech.ac.kr).